



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

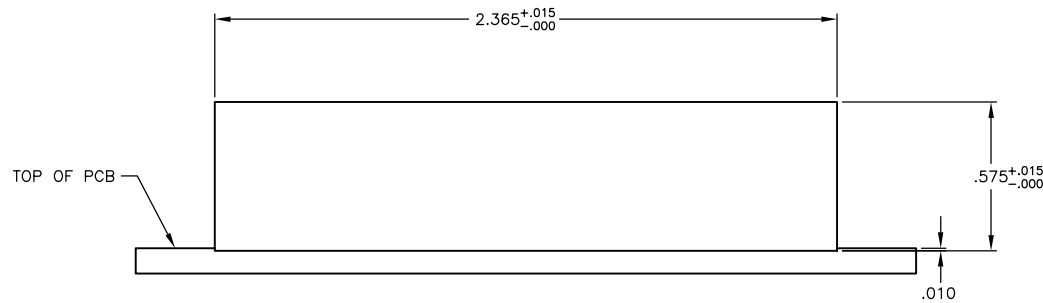
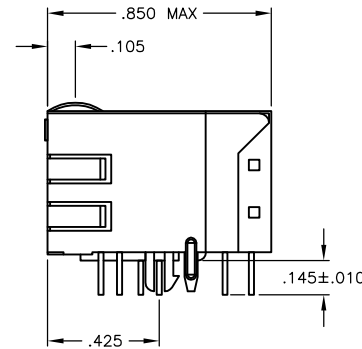
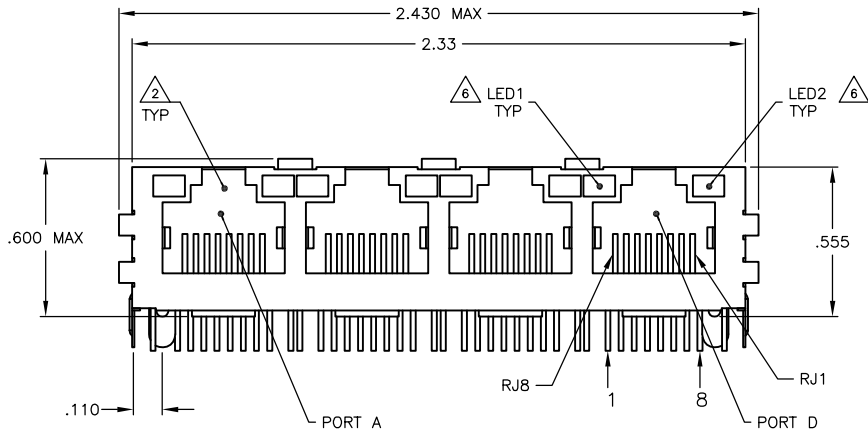
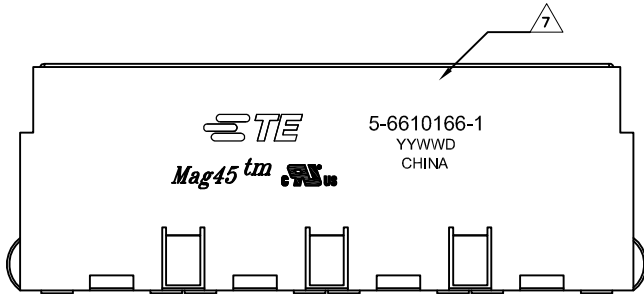
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MECHANICAL:



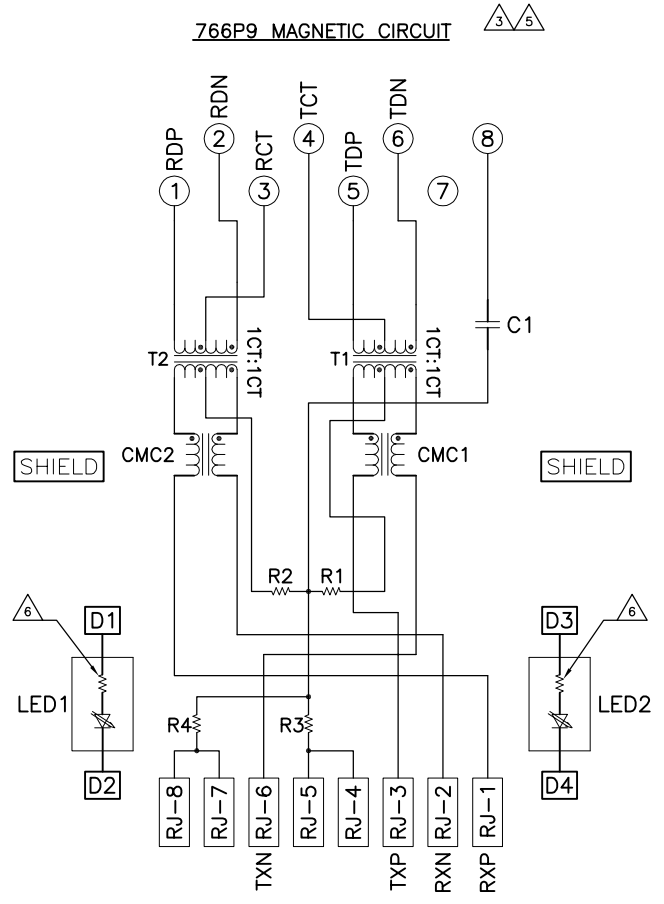
1X4 SUGGESTED PANEL CUTOUT

1. MATERIALS:
 - HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
 - SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30 μ INCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100 μ INCH MIN SAC SOLDER.
 - MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50 μ INCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50 μ INCH MIN HARD GOLD FINISH PLATE. SOLDER TAILS WITH 100 μ INCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
 - LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" X .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80 μ INCH SILVER OVER 40 μ INCH NICKEL UNDERPLATE OVER 40 μ INCH COPPER UNDERPLATE. POST-PLATED WITH 100 μ INCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.
2. RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.
3. MAGNETICS
 - IMPEDANCE: 100 OHMS
 - TURNS RATIO (CHIP-CABLE): TX = 1:1, RX = 1:1
 - OPEN CIRCUIT INDUCTANCE (OCL): 350 μ H MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, TX AND RX
 - PERFORMANCE @ 25°C:
 - INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 - RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 - 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 - 12dB MIN FROM 60.1MHz TO 80MHz
 - CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 - 33-20*LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
 - COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 - ISOLATION VOLTAGE: COMPLIES WITH IEEE802.3 2002, PARA 23.5.1.1, ITEM b.
4. OPERATING TEMPERATURE: FROM 0°C TO +70°C.
5. INDICATED CONNECTIONS ARE FOR HUB CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL AND SUPPORT AUTO-MDI/MDIX.
6. LEDs WITH BUILT-IN RESISTOR
 - LEDs ARE DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA.
 - LED COLOR: DOMINANT WAVELENGTH (AD): GREEN 568 nm TYP @ VF=5V
 - FORWARD CURRENT (IF): GREEN 12mA TYP @ VF=5V
 - DOMINANT WAVELENGTH (AD): YELLOW 588 nm TYP @ VF=5V
 - FORWARD CURRENT (IF): YELLOW 13mA TYP @ VF=5V
7. TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.
8. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS. PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

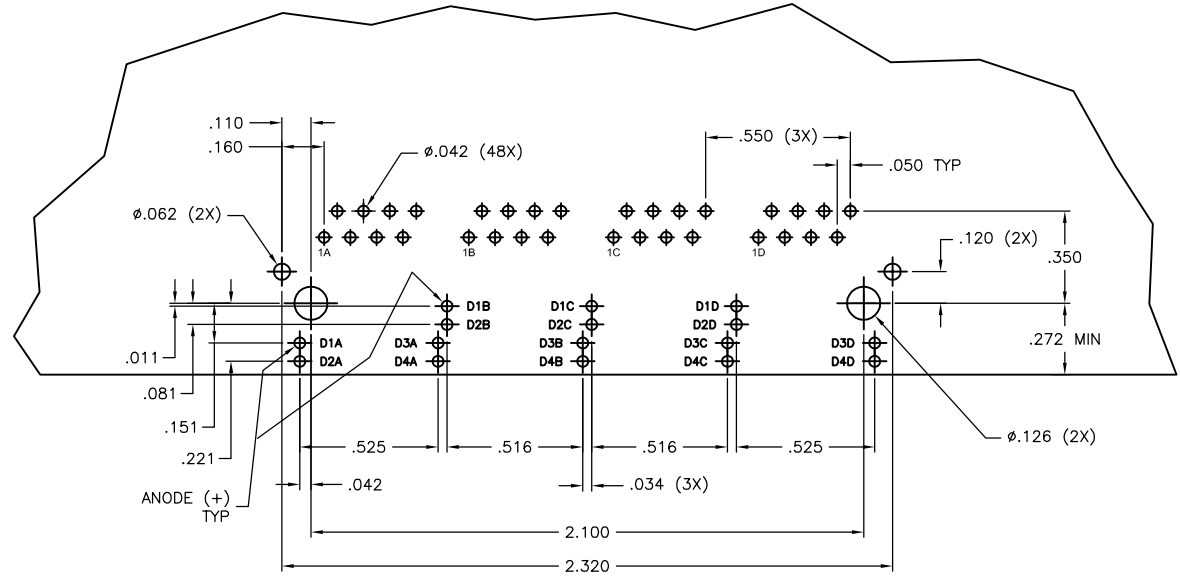
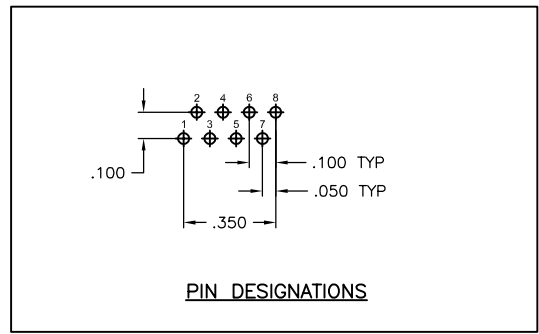
GREEN	YELLOW	5-6610166-1
LED1 \triangle 6	LED2 \triangle 6	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV. 5-ATTACIA - (REVISION)	DATE
DIMENSIONS: INCHES		DR. T. FAROLE	10/08/2012
MATERIAL: \triangle		APP. T. FAROLE	10/08/2012
FINISH: \triangle		DATE CODE	1008-2100
CUSTOMER DRAWING		SIZE	A1
SCALE: 4:1		QTY	1
SHEET		REV	2
DRAWING NO: 100779		DATE	10/08/2012
PART NO: 5-6610166		BY	JC
DESCRIPTION: 1X4 MAG45(TM) MODULAR JACK, 7HS SCHEMATIC, 768P9 MAGNETIC CIRCUIT, SHIELDED, DECOUPLING CAPACITOR, WITH RESISTOR LEADS		CHK	KZ

766P9 MAGNETIC CIRCUIT



C1=1000pF, 2kV CAPACITOR
 R1-R4 = 75 OHMS, 1/16W RESISTORS



SUGGESTED PCB LAYOUT
 (Component Side)

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV. 05_ATTACIA - 00000000		DATE	
DIMENSIONS:		UNIT: MILLIMETER		SCALE	
MATERIAL:		FINISH:		CUSTOMER DRAWING	
DRAWN BY:		CHECKED BY:		DATE:	
DESIGNED BY:		APPROVED BY:		DATE:	
PROJECT NO:		108-2100		SCALE: 4:1	
APPLICATION SPEC:		SIZE: A1		SHEET: 2 of 2	
MATERIAL:		PART NO: 00779		REV: C	
FINISH:		C=6610166		REV: G	